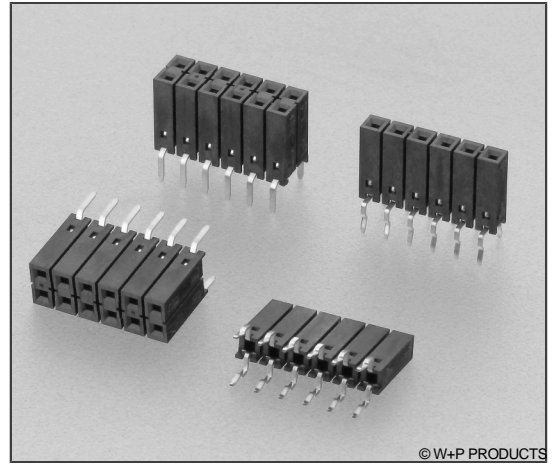


46-289 Economy Version

Buchsenleisten RM 2,54mm, gerade, 1-/2-reihig – BH 8,5mm, durchsteckbar
Female Headers, 2.54mm Pitch, Straight, Single / Double Row – 8.5mm Profile, Pass Through

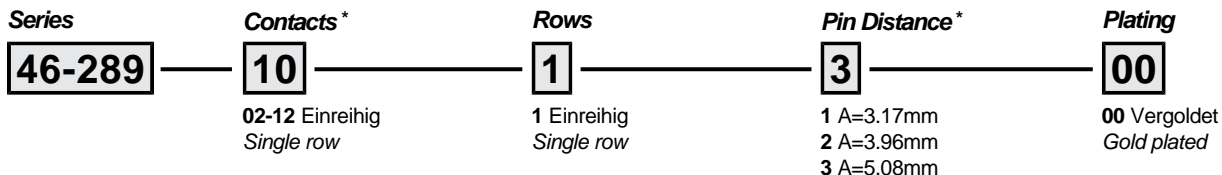
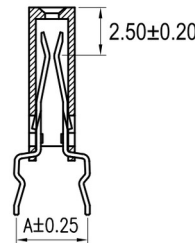
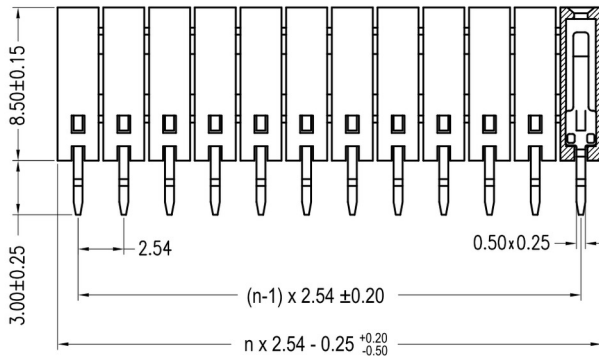
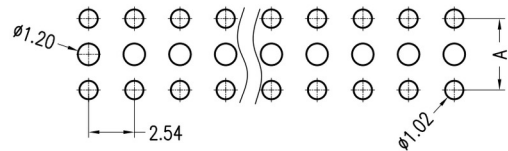
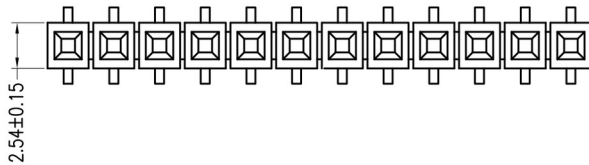
Technische Daten / Technical Data

Isolierkörper	Thermoplast, nach UL94 V-0
Insulator	Thermoplastic, rated UL94 V-0
Kontaktmaterial	Kupferlegierung
Contact Material	Copper alloy
Kontaktoberfläche	Au über Ni
Contact Surface	Au over Ni
Durchgangswiderstand	< 20 mΩ
Contact Resistance	< 20 mΩ
Isolationswiderstand	> 1000 MΩ
Insulation Resistance	> 1000 MΩ
Spannungsfestigkeit	1000 V AC/DC
Test Voltage	1000 V AC/DC
Nennstrom	3 A
Current Rating	3 A
Temperaturbereich	-40 °C ~ +105 °C
Temperature Range	-40 °C ~ +105 °C
Verarbeitung	260 °C für 5 sec. / 230 °C für 30-60 sec.
Processing	260 °C for 5 sec. / 230 °C for 30-60 sec.



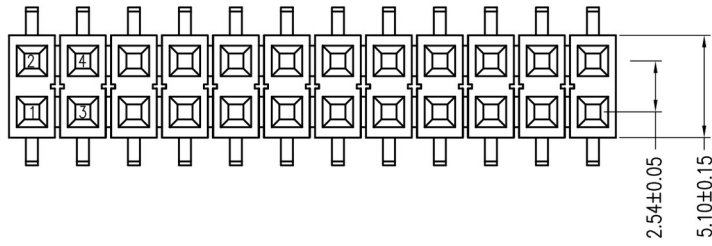
Doppelfederkontakte für Vierkantstifte 0,635mm.
 Dual beam contacts accept 0.635mm square pins.

Recommended PCB Layout (Top Side)
 (PCB BOARD TOLERANCE ±0.05)

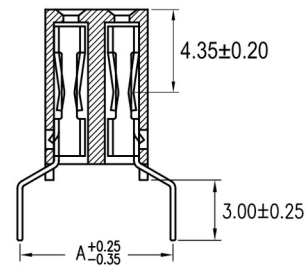
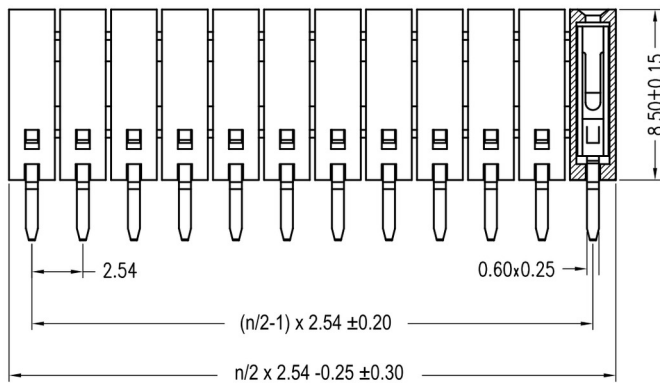
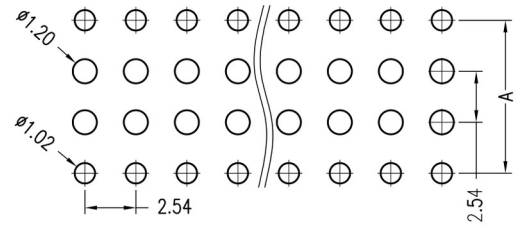


46-289 Economy Version

Buchsenleisten RM 2,54mm, gerade, 1-/2-reihig – BH 8,5mm, durchsteckbar
 Female Headers, 2.54mm Pitch, Straight, Single / Double Row – 8.5mm Profile, Pass Through



Recommended PCB Layout (Top Side)
 (PCB BOARD TOLERANCE ±0.05)



Series	Contacts*	Rows	Pin Distance*	Plating
46-289	20 02-24 Zweireihig Double row	2 2 Zweireihig Double row	4 4 A=6.50mm 5 A=7.62mm	00 00 Vergoldet Gold plated

* Dies ist ein **Bestellbeispiel** - bitte durch Ihre Spezifikationen ersetzen.
 * This is an **order example** - please replace by your specifications.

Reflow-Lötempfehlung für kurze Lötzeiten

Die Bauteile sollten gemäß folgendem Temperatur-Profil in Anlehnung an die IPC/JEDEC J-STD-020C für bleifreies Löten im Reflow-Verfahren verarbeitet werden (Maximalwerte).

Profileigenschaft	Kennwert
Temperatur Minimum T_{Smin}	150 °C
Temperatur Maximum T_{Smax}	200 °C
Dauer $T_{Smin} - T_{Smax}$	60 – 180s
Temperatur Lötbereich T_L	untere Temperaturangabe [°C]
Verweildauer oberhalb T_L	laut Angabe im Datenblatt [sec]
Ramp-Up Rate $T_{Smax} - T_P$	max. 3 °C / s
Höchsttemperatur T_P	obere Temperaturangabe [°C]
Dauer Höchsttemperatur	laut Angabe im Datenblatt [sec]
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	6 °C / s
Dauer 25 °C – Höchsttemperatur T_P	max. 8m

Reflow Soldering Recommendation For Shorter Peak Times

Items should be soldered according to IPC/JEDEC J-STD-020C temperature profile for leadfree reflow soldering (maximum values).

Profile Feature	Key Values
Minimum Temperature T_{Smin}	150 °C
Maximum Temperatur T_{Smax}	200 °C
Duration $T_{Smin} - T_{Smax}$	60 – 180s
Soldering Range Temperature T_L	Lower Temperature [°C]
Duration above T_L	Acc. to datasheet [sec]
Ramp-Up Rate $T_{Smax} - T_P$	max. 3 °C / s
Peak Temperature T_P	Upper Temperature [°C]
Duration Peak Temperature	Acc. to datasheet [sec]
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	6 °C / s
Duration 25°C - Peak Temp. T_P	max. 8min

